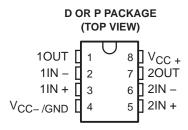
SLOS086 - D2567, OCTOBER 1979 - REVISED OCTOBER 1990

- Wide Range of Supply Voltages
 Single Supply . . . 5 V to 30 V
 Dual Supplies . . . ± 2.5 V to ± 15 V
- Class AB Output Stage
- True Differential Input Stage
- Low Input Bias Current
- Internal Frequency Compensation
- Short-Circuit Protection

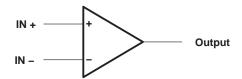
description

The TL322C and the TL322I are dual operational amplifiers similar in performance to the uA741 but with several distinct advantages. They are designed to operate from a single supply over a range of voltages from 5 V to 30 V. Operation from split supplies is also possible provided the difference between the two supplies is 5 V to 30 V. The common-mode input range includes the negative supply. Output range is from the negative supply to $V_{\rm CC}$ –1.5 V. Quiescent supply currents per amplifier are typically less than one-half those of the uA741.

The TL322C is characterized for operation from 0°C to 70°C. The TL322I is characterized for operation from –40°C to 85°C.



symbol (each amplifier)

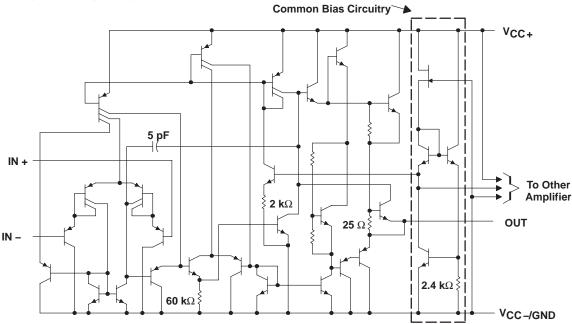


AVAILABLE OPTIONS

		PACKAGE						
TA	V _{IO} MAX AT 25°C	SMALL OUTLINE (D)	PLASTIC DIP (P)					
0°C to 70°c	10 mV	TL322CD	TL322CP					
0°C to 70°c	8 mV	TL322ID	TL322IP					

D packages are available taped and reeled. Add R suffix to device type, (e.g., TL322CDR).

schematic (each amplifier)



All component values shown are nominal.



TL322C, TL322I **DUAL LOW-POWER OPERATIONAL AMPLIFIERS**

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	TL322C	TL322I	UNIT
Supply voltage V _{CC+} (see Note 1)	18	18	V
Supply voltage V _{CC} (see Note 1)	-18	-18	V
Supply voltage V _{CC+} (with respect to V _{CC-})	36	36	V
Differential input voltage (see Note 2)	±36	±36	V
Input voltage (see Notes 1 and 3)	±18	±18	V
Continuous total power disspation	See Diss	ipation Rating Tal	ole
Operating free-air temperature range	0 to 70	-40 to 85	°C
Storage temperature range	-65 to 150	-65 to 150	°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260	260	°C

- NOTES: 1. These voltage values are with respect to the midpoint between $\rm V_{CC\,+}$ and $\rm V_{CC\,-}$
 - 2. Differential voltages are at the noninverting input terminal with respect to the inverting input terminal.
 - 3. Neither input must ever be more positive than V_{CC+} or more negative than V_{CC-} .

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \leq 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR	DERATE ABOVE T _A	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
D	680 mW	5.8 mW/°C	33°C	464 mW	377 mW
Р	680 mW	8.0 mW/°C	65°C	640 mW	520 mW

recommended operating conditions

	MIN	NOM MAX	UNIT
Single supply voltage, V _{CC}	5	30	V
Dual supply voltage, V _{CC+}	2.5	15	V
Dual supply voltage, V _{CC} _	- 2.5	– 15	V

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electrical characteristics at specified free-air temperature, $V_{\text{CC}\pm}$ = 15 V (unless otherwise noted)

	DADAMETED	TEOT CONDI	TIONOT	1	L322C		TL322I			UNIT	
	PARAMETER	TEST CONDI	IIONSI	MIN	TYP	MAX	MIN	TYP	MAX	UNII	
\/10	Input offset voltage	$V_{O} = 0$,	25°C		2	10		2	8	mV	
VIO	Input onset voltage	$R_S = 50 \Omega$	Full range			12			10	IIIV	
αVIO	Temperature coefficient of input offset voltage	$V_O = 0$, $R_S = 50 \Omega$	25°C		10			10		μV/°C	
lio	Input offset current	V _O = 0	25°C		30	50		30	75	nA	
ΙΟ	input onset current	vO = 0	Full range			200			250	IIA	
αΙΙΟ	Temperature coefficient of input offset current	V _O = 0	25°C		50			50		pA/°C	
lin.	Input bias current	V _O = 0	25°C		-0.2	-0.5		-0.2	-0.5	μА	
IB	input bias current	νO = 0	Full range			-0.8			-1	μΑ	
	Common mode innut			VCC-	VCC-		VCC-	VCC-			
VICR	Common-mode input voltage range‡		25°C	to	to		to	to		V	
voltage ranger				13	13.5		13	13.5			
		$R_L = 10 \text{ k}\Omega$	25°C	±12	±13.5		±12	±12.5			
Vом	Peak output voltage swing	5 510	25°C	±10	±13		±10	±12		V	
		$R_L = 2 k\Omega$	Full range	±10			±10				
	Large-signal differential	$V_{O} = \pm 10 \text{ V},$	25°C	20	200		20	200			
AVD	voltage amplification	$R_L = 2 k\Omega$	Full range	15			15			V/mV	
B _{OM}	Maximum-output- swing bandwidth	$V_{O(PP)} = 20 \text{ V},$ $A_{VD} = 1,$ $THD \le 5\%,$ $R_{L} = 2 \text{ k}\Omega$	25°C		9			9		kHz	
B ₁	Unity-gain bandwidth	$V_O = 50 \text{ mV},$ $R_L = 10 \text{ k}\Omega$	25°C		1			1		MHz	
фm	Phase margin	$R_L = 2 k\Omega$, $C_L = 200 pF$	25°C		60°			60°			
rį	Input resistance	f = 20 Hz	25°C	0.3	1		0.3	1		МΩ	
r _O	Output resistance	f = 20 Hz	25°C		75			75		Ω	
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR} \text{ min},$ $R_S = 50 \Omega$	25°C	70	90		70	90		dB	
kSVS	Supply voltage sensitivity $(\Delta V_{IO}/\Delta V_{CC})$	$V_{CC} = \pm 2.5 \text{ V to}$ $\pm 15 \text{ V},$ $R_S = 50 \Omega$	25°C		30	150		30	150	μV/V	
los	Short-circuit output current§	VO = 0	25°C	±10	±30	±45	±10	±30	±45	mA	
ICC	Total supply current	$V_O = 0$, No load	25°C		1.4	4		1.4	4	mA	

[†] All characteristics are under open-loop conditions unless otherwise noted. Full range for TA is 0°C to 70°C for TL322C and -40°C to 85°C for



[†] The V_{ICR} limits are directly linked volt-for-volt to supply voltage; the positive limit is 2 V less than V_{CC+}. § Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.

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electrical characteristics, V_{CC+} = 5 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS†		TL322C			TL322I		UNIT
	PARAMETER	TEST CONDITIONS!	MIN	TYP	MAX	MIN	TYP	MAX	UNII
VIO	Input offset voltage	$V_0 = 2.5 \text{ V}, R_S = 50 \Omega$		2	10			8	mV
IIO	Input offset current	V _O = 2.5 V		30	50			75	nA
I _{IB}	Input bias current			-0.2	-0.5			-0.5	pА
		$R_L = 10 \text{ k}\Omega$	3.3	3.5		3.3	3.5		
V _{OM} Peak output voltage swing [‡]		$R_L = 10 \text{ k}\Omega$	V 47						V
		V _{CC+} = 5 V to 30 V	V _{CC+} -1.7			V _{CC+} -1.7			
	Large-signal differential	$V_0 = 1.7 \text{ V to } 3.3 \text{ V},$	00	000		-00	000		\//\/
AVD	voltage amplification	$R_L = 2 k\Omega$	20	20 200		20	200		V/mV
ksvs	Supply voltage sensitivity $(\Delta V_{IO}/\Delta V_{CC+})$	$V_{CC} = \pm 2.5 \text{ V to } \pm 15 \text{ V}$			150			150	μV/V
Icc	Supply current	V _O = 2.5 V, No load		1.2	4		1.2	4	mA
V ₀₁ /V ₀₂	Crosstalk attenuation	A _{VD} = 100, f = 1 kHz to 20 kHz		120			120		dB

[†] All characteristics are specified under open-loop conditions.

switching characteristics, $V_{CC+} = 15 \text{ V}$, $V_{CC-} = -15 \text{ V}$ $A_{VD} = 1$, $T_A = 25^{\circ}\text{C}$ (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN TYP MAX	UNIT
SR	Slew rate at unity gain	$V_I = \pm 10 \text{ V}$, $C_L = 100 \text{ pF}$, See Figure 1	0.6	V/μs
t _r	Rise time	1)/ 50 m// 0 400 mF B 4010	0.35	μs
t _f	Fall time	$\Delta V_O = 50$ mV, $C_L = 100$ pF, $R_L = 10$ k Ω , See Figure 1	0.35	μs
	Overshoot factor	See Figure 1	20%	
	Crossover distortion	$V_{I(PP)} = 30 \text{ mV}, V_{O(PP)} = 2 \text{ V}, f = 10 \text{ kHz}$	1%	

PARAMETER MEASUREMENT INFORMATION

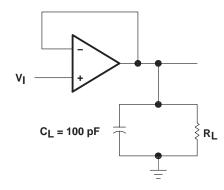


Figure 1. Unity-Gain Amplifier

[‡] Output will swing essentially to ground.

TYPICAL CHARACTERISTICS[†]

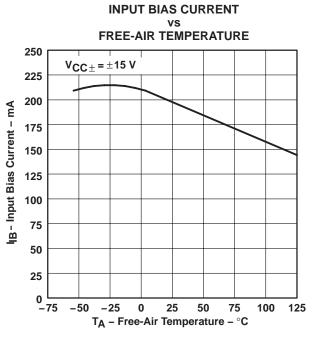
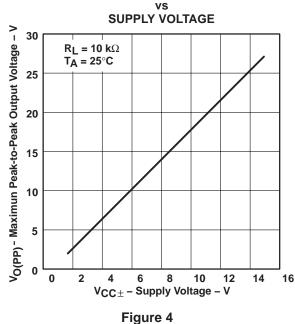


Figure 2

MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE



INPUT BIAS CURRENT VS SUPPLY VOLTAGE

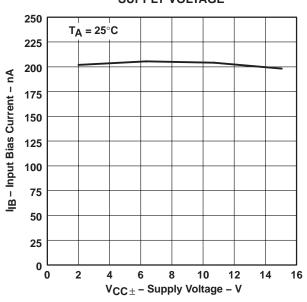


Figure 3

MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE

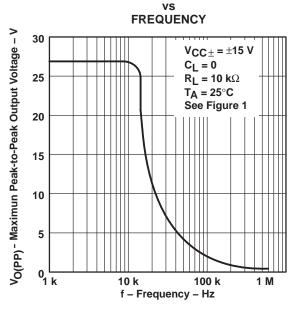


Figure 5

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION

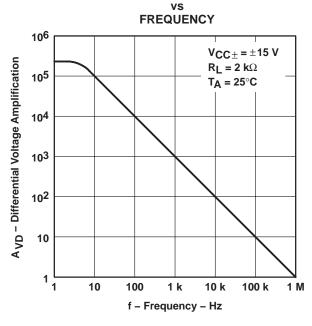


Figure 6

VOLTAGE-FOLLOWER LARGE-SIGNAL PULSE RESPONSE

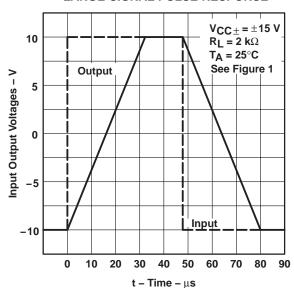


Figure 7





.com 23-Apr-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
TL322CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL322CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL322CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL322CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL322CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL322CP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
TL322CP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
TL322ID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL322ID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL322IP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
TL322IP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL322CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL322CDR	SOIC	D	8	2500	340.5	338.1	20.6

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

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